

AMENDMENTS TO THE CLAIMS

The following is a complete, marked-up listing of revised claims with a status identifier in parenthesis, underlined text indicating insertions, and strike through and/or double-bracketed text indicating deletions.

LISTING OF CLAIMS

1. (Currently Amended) A process for assembling at least one electronic component made up of a chip provided with contacts on one of the faces of the chip, said contacts being set off on a conductive film constituting ~~including~~ flat conductive areas that extend the contacts of the chip in a plane over the chip, the conductive areas are being connected to conductive tracks placed on a surface of a ~~flat~~ planar insulating substrate, comprising:

- placing the substrate on a work surface, the face including conductive tracks being oriented upwards,
- placing the electronic component into a cavity of the substrate situated in a zone including the conductive tracks, the chip being inserted into the cavity, the conductive areas of the electronic component coming into contact with the corresponding conductive tracks of the substrate, and
- applying a layer of insulating material which extends concurrently on the electronic component and at least on the zone of the substrate surrounding said electronic component, wherein the conductive areas of the electronic component and the conductive tracks of the substrate are in contact to achieve an electric connection via a pressure of application of the insulating material layer on the electronic

component, and configured to rub together when repeated stressed are exerted on the substrate.

2. (Currently Amended) The process according to claim 1, wherein the electronic component is ~~made up of a chip provided with contacts on one of the faces of the chip, said contacts being set off on a conductive film constituting the contact areas that extend the contacts of the chip, the opposite face of the chip being coated by~~ coated by an insulating material on the face of the chip opposite to the face provided with contacts.

3. (Currently Amended) The process according to claim [[2]] 1, wherein the layer of insulating material is made up of a first substrate including a cavity into which the chip of the electronic component is inserted, the conductive areas of said electronic component being applied against the surface of the first substrate ~~the coated face of the electronic component being inside the cavity, the contact areas of said electronic component connecting with~~ to corresponding conductive areas surfaces of a second substrate placed on the work surface.

4-5. (Cancelled)

6. (Currently Amended) The process according to claim [[5]] 1, wherein the cavity of the electronic component is obtained by heating the chip of the electronic component, then pressing said chip into the substrate material so that the ~~contact~~ conductive areas of said electronic component are applied against the surface of the substrate.

7-8. (Cancelled)

9. (Previously Presented) The process according to claim 1 wherein the cavity of the electronic component is formed by milling or by stamping a window.

10. (Cancelled)

11. (Currently Amended) The process according to claim 1, wherein the electronic component is made up of a module including a set of flat contacts on one of the faces of the module and ~~on the opposite face conductive areas linked to each contact of the set.~~module, each contact of the set being linked with a contact area on the opposite face.

12. (Currently Amended) The process according to claim 11, wherein the module is inserted into a cavity provided with a window cut into a first substrate with a thickness approximately equal to that of the module, the set of flat contacts shows on the surface level of said first substrate and the conductive areas of the opposite face lean against the conductive tracks of a second substrate assembled on the first substrate.

13. (Previously Presented) The process according to claim 12, wherein at least one module or a supplementary chip is mounted in one of the substrates, said module including conductive areas connected by pressure on the corresponding conductive tracks of either of the substrates.

14. (Previously Presented) The process according to claim 13, further comprising a supplementary step of gluing and pressing the assembly formed by the superposition of the substrates.